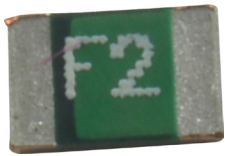


Surface Mountable PTC Resettable Fuse



RoHS
Compliant



Specifications:

Applications : All high-density boards.
 Product Features : Small surface mountable, solid state, faster time to trip than standard SMD devices, lower resistance than standard SMD devices.
 Max. Voltage : 6V to 15V.
 Temperature Range : -40°C to 85°C.

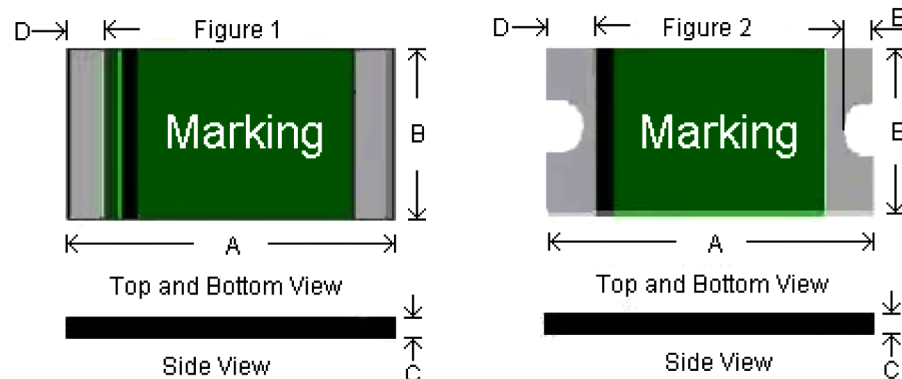
Electrical Characteristics (23°C):

Part Number	Hold Current	Trip Current	Rated Voltage	Max. Current	Typical Power	Max Time to Trip		Resistance	
						Current	Time	R _{MIN}	R _{1MAX}
	I _H , A	I _T , A	V _{MAX} , V DC	I _{MAX} , A	P _d , W	Amp	Sec.	Ω	Ω
MC36206	0.2	0.5	9	100	0.5	8	0.02	0.4	3.5
MC36210	0.35	0.75	6	100	0.5	8	0.1	0.25	1.2
MC36213	0.5	1	6	100	0.5	8	0.1	0.15	0.85
MC36215	0.75	1.5	6	100	0.6	8	0.2	0.09	0.35
MC36220	1	1.95	6	100	0.6	8	0.3	0.06	0.21

I_H = Hold current-maximum current at which the device will not trip at 23°C still air.
 I_T = Trip current-minimum current at which the device will always trip at 23°C still air.
 V_{MAX} = Maximum voltage device can withstand without damage at it rated current. (I_{MAX})
 I_{MAX} = Maximum fault current device can withstand without damage at rated voltage (V_{MAX}).
 P_d = Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.
 R_{MIN} = Minimum device resistance at 23°C prior to tripping.
 R_{1MAX} = Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad characteristics
 Termination pad materials : Pure Tin

Production Dimensions



www.element14.com
 www.farnell.com
 www.newark.com



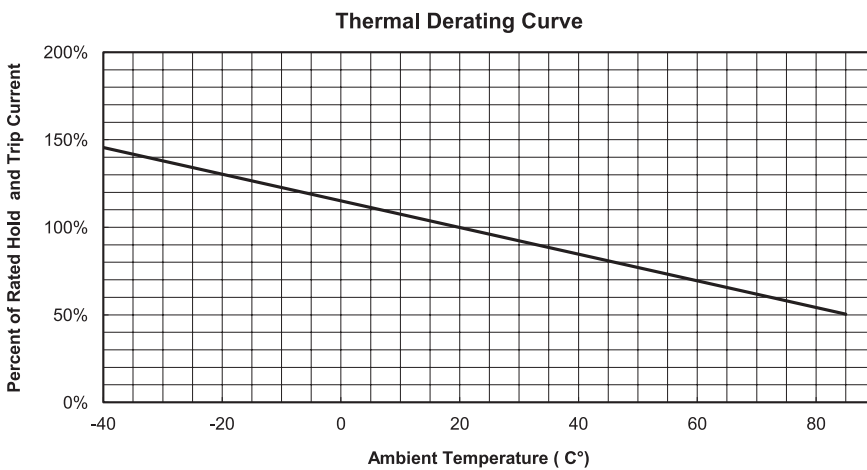
Surface Mountable PTC Resettable Fuse



Part Number	Figure	A		B		C		D		E	
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
MC36206	1	2	2.3	1.2	1.5	0.3	1	0.2	0.6	-	-
MC36210	1	2	2.3	1.2	1.5	0.25	0.75	0.2	0.6	-	-
MC36213	2	2	2.3	1.2	1.5	0.4	0.9	0.2	0.6	0.1	0.45
MC36215	2	2	2.3	1.2	1.5	0.55	1.25	0.2	0.6	0.1	0.45
MC36220	2	2	2.3	1.2	1.5	0.75	1.8	0.2	0.6	0.1	0.45

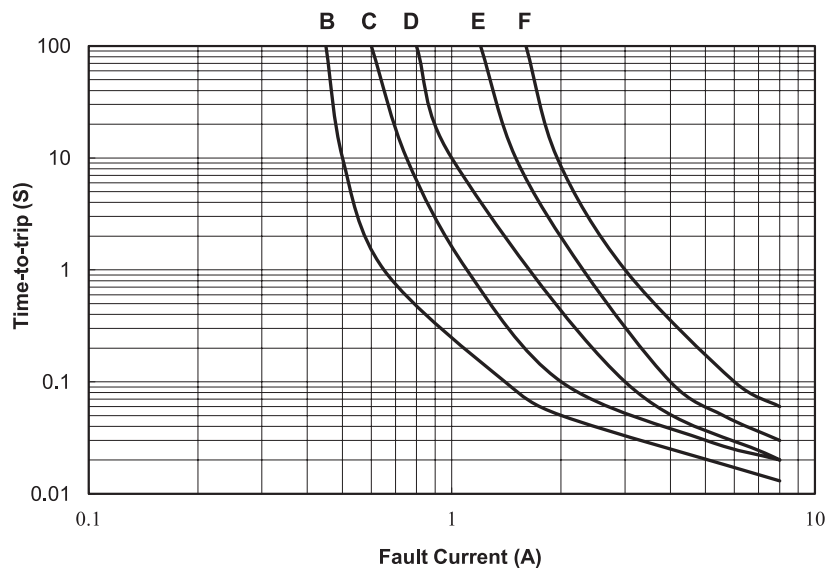
Dimensions : Millimetres

Thermal Derating Curve



Typical Time-To-Trip at 23°C

- B = MC36206**
- C = MC36210**
- D = MC36213**
- E = MC36215**
- F = MC36220**



Surface Mountable PTC Resettable Fuse



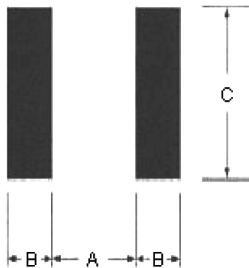
Material Specification

Terminal pad material : Pure tin.

Soldering characteristics : Meets EIA specification RS 186-9E, ANSI/J-std-002 category 3.

Pad Layouts Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each 0805 device.



Pad Dimensions

Device	A Nominal	B Nominal	C Nominal
All 0805 Series	1.2	1	1.5

Dimensions : Millimetres

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Ts maximum to TP)	3°C/second maximum
Preheat:	
Temperature Minimum (Ts minimum)	150°C
Temperature Maximum (Ts maximum)	200°C
Time (ts minimum to ts maximum)	60-180 seconds
Time maintained above:	
Temperature (TL)	217°C
Time (tL)	60-150 seconds
Peak/Classification Temperature (TP):	260°C
Time within 5°C of actual Peak:	
Temperature (tP)	20-40 seconds
Ramp-Down Rate	6°C/second maximum
Time 25°C to Peak Temperature	8 minutes maximum

Note 1: All temperatures refer to of the package, measured on the package body surface.

Solder reflow

Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

1. Recommended max past thickness > 0.25mm.
2. Devices can be cleaned using standard methods and aqueous solvent.
3. Rework use standard industry practices.
4. Storage Environment : < 30°C/60% RH.

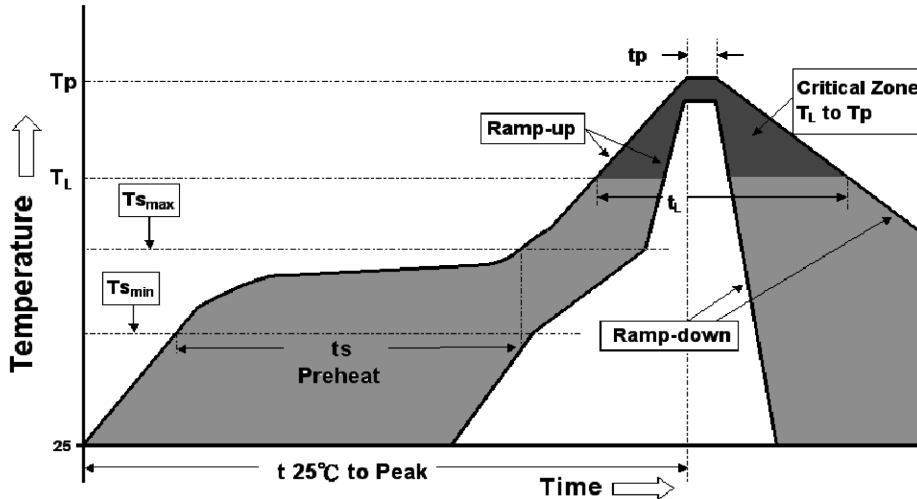
Caution:

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.

Surface Mountable PTC Resettable Fuse



Reflow Profile



Part Number Table

Description	Part Number
Surface Mountable PTC Resettable Fuse	MC36206
	MC36210
	MC36213
	MC36215
	MC36220

Important Notice : This data sheet and its contents (the "Information") belong to the members of the Premier Farnell group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for their purpose and not make any assumptions based on information included or omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp is the registered trademark of the Group. © Premier Farnell Limited 2016.

